

7022-000-0077

Date : 22-aug-19	Layers : 4	Revision : 3	Customer : NXP Nijmegen	Page : 1 of 1
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			Thickness	Type
Solder Mask				
Copper	1		35 µm	
Prepreg			360 µm	
Copper	2		35 µm	
Core			710 µm	
Copper	3		35 µm	
Prepreg			360 µm	
Copper	4		35 µm	
Solder Mask				
Total:			1570 µm	